



RADSOK® Power to Board Connectors

BACKGROUND

Modern day electronics require significant increases in the amount of power needed for their board applications. To simplify the application design, users incorporate busbars to bring power to the board. The RADSERT™ simplifies the distribution of power, while allowing the design engineer to achieve size and weight reductions.

PROBLEM

Conventional interconnects can not handle the higher power requirements of modern electronics board applications. The common solution to increase power to the board is to increase the thickness of the copper layers in the board. This is usually costly and traps heat within the PCB. Other options are to bring additional wires to the board which creates a "bundle" of wire. This option takes up space on the board and doesn't allow proper air flow, which can cause failures.

AIO SOLUTION

Amphenol RADSOK® offers many options for high current with single-point connections to the PCB. The PCB RADSERT's™ compact footprint design provides up to 70 AMPS to the board which allows more surface space and provides more flexibility of board design. They are available in either press-fit or solder versions.

The RADSOK® Powerblok's™ compact footprint 1/2" x 1/2" carries up to 70 Amp for backplane power interface w/compliant pins. It also offers a touch-proof cover.

The RADSOK® PGY's™ are available in two different sizes, 3.6mm and 5.7mm and can bring up to 120A to the board. The radial design of the RADSOK® gives you more surface area with many contact points for appropriate heat dissipation at the pin and socket interface. This lowers temperature rise and reduces potential failures.